

S/N 09/733289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiao-Chun Mu et al.

Examiner: DiLinh Nguyen

Serial No.: 09/733289

Group Art Unit: 2814

Filed: December 8, 2000

Docket No.: 884.798US1

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

*Response*  
*#16/8*  
*5-21-03*  
*J. Antin*

RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicant has reviewed the Office Action mailed on January 10, 2003.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from April 10, 2003 to May 10, 2003. Since May 10, 2003 falls on a Saturday, it is believed that the due date carries over to the next business day, May 12, 2003.

